# Design of 1R/1W 8T SRAM Cell

**ECE-611 (Memory Design and Testing)** 

Group - 1

**Group Members:** 

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## Design specifications & understanding:



#### **Given specification:**

- Vmin (read port) = 0.81V
- Vmin (write port) = 1.08V when mux 16
- Vmin (write port) = 0.81V when mux 1 with WL Boost Icell = 100uA at wc, 1.08V

#### **Understanding:**

- Sizing of write port is determined on the basis of SNM and write functionality.
- Icell needs to be 100uA at worst PVT condition, i.e. SS, Low voltage 1.08V, 125C.
- ❖ Icell determines the sizing of NMOS stack at the read ports, Icell ↑, Read speed ↑.

#### Challenges



- Eldo commands for various FOM simulations to be done for SNM, Icell, Write Time, Write Margin etc.
- Six sigma qualification of SNM, such that sizing should ensure that the lowest and worst PVT has required
   6-7 sigma margin only.
- Obtaining minimum area bitcell layout to meet design requirements efficiently.
- Designing array structure by flipping and sharing bitcell and routing various shared signals with different metal layers across the array in the minimum area possible.
- Overcoming challenges in creating layouts that meet Design Rule Checks (DRC) and Layout versus
   Schematic (LVS) criteria, ensuring cleanliness and compliance with design standards.
- We encountered challenge in achieving sigma qualification for bitcell figure of merits (FOMs).



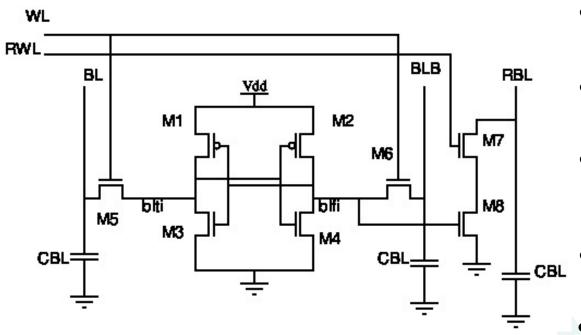


Fig 1: Schematic of 8T SRAM cell

#### **KEY POINTS:**

- The Read and Write ports are decoupled.
- NMOS stack in Read Port is sized according to Icell.
- More stable and faster cell, suitable for LV operations as retention voltage gets reduced.
  - Additionally the cell can also use ports as 1RW/1R.
- I\_Pon is the additional FOM that needs to be taken care to avoid accidental read by SA.

# Sizings



Transistor	Sizings (W/L)		Constraint	
Transistor	Initial	Final	Constraint	
Read Port (M7, M8)	0.220/0.085	0.200/0.08	Icell=100uA	
Pull Up (M1,M2)	0.135/0.085	0.135/0.085	Minimum sized device	
Pass Gate (M5,M6)	0.175/0.085	0.170/0.085	Read SNM 6-Sigma Write Functionality	
Pull Down (M3,M4)	0.260/0.085	0.210/0.085	Read SNM 6-Sigma Write Functionality	

# Verification Plan, Stimuli and PVT conditions



	FOMs	PROCESS CORNER	STIMULI	PRE SIMULATION VALUE	POST SIMULATION VALUE
Read SNM		FS, 1.08V, 125C	BL, WL = High	_	132.64 mV
		FS, 0.81V, 125C		_	110.16 mV
Cell Current		SS, 1.08V, 125C	RWL, WL = High, Q_Bar = 1	151.78 μΑ	123.88 μΑ
		SS, 0.81V, 125C		105.12 μΑ	97.27 μΑ
Write Margins	WL Write Margin	SF, 0.81V, 125C	BLB=High, BL=Low, WL=High	0.607 V	0.570 V
		SF, 0.81V, -40C		0.61 V	0.565 V
	BL Write Margin	SF, 0.81V, 125C		_	0.530 V
		SF, 0.81V, -40C		_	0.567 V

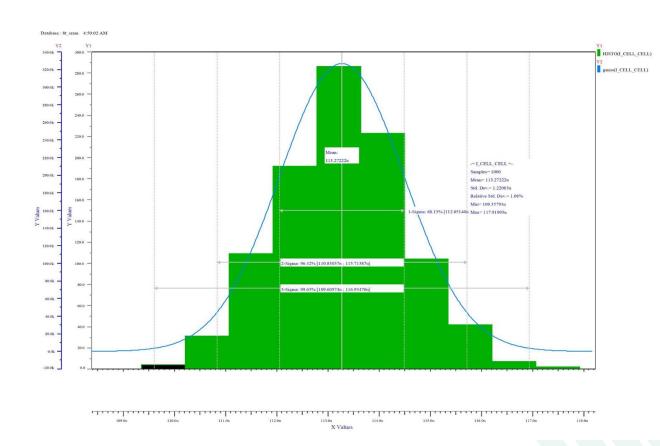
# Verification Plan, Stimuli and PVT conditions



FOMs	PROCESS CORNER	STIMULI	PRE SIMULATION VALUE	POST SIMULATION VALUE
Write Time	SF, 0.81V, -40C	BLB=High, BL=Low,	6.24 ns	12.194 ns
	TT, 0.81V, -40C	WL=High	3.118 ns	10.23 ns
Leakage	FF, 1.08V, 125C	All devices are in	77.35 pA	430 pA
	FF, 0.81V, 25C	OFF state. WL, RWL =0	29.67 pA	81 pA
I_Partial_(ON) (Additional FOM for 8T)	FS, 1.08V, 125C	RWL = High, Q = 1 Q_Bar = 0		2.4008 μΑ

# PDF for Icell (Post Layout)





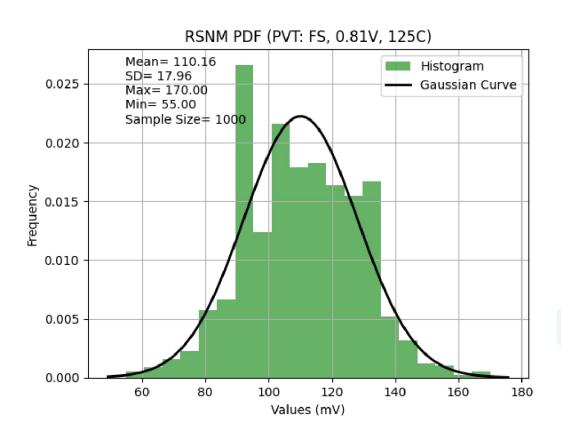
#### Icell @SS, 1.08V, 125C Six Sigma Qualified

Mean (
$$\mu$$
) = 113.27  $\mu$ A SD ( $\sigma$ ) = 1.221

$$\mu - 6*(\sigma) = 105.95 \ \mu A > 100 \ \mu A$$

## PDF for SNM (Post Layout)





#### SNM @FS, 0.81V, 125C Six Sigma Qualified

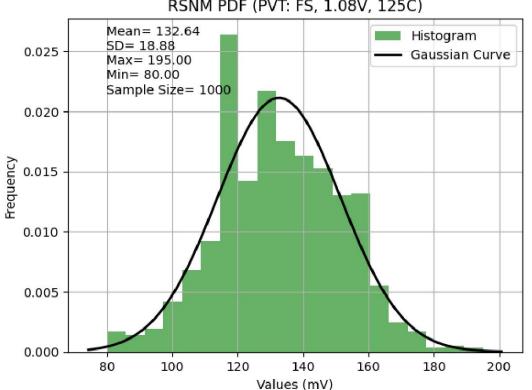
Mean ( $\mu$ ) = 110.16 mV SD ( $\sigma$ ) = 17.96

$$\mu/(\sigma) = 6.1336$$

# PDF for SNM (Post Layout)







#### SNM @FS, 1.08V, 125C Six Sigma Qualified

Mean (
$$\mu$$
) = 132.64 mV SD ( $\sigma$ ) = 18.88

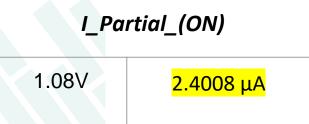
$$\mu/(\sigma) = 7.025$$

# I\_Partial\_(ON)

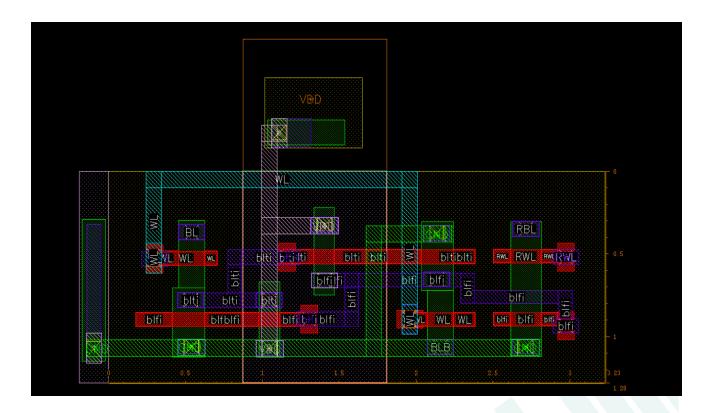




- In an scenario when, Q = 1.08 v Q' = 0v
- Ideally, RBL should not discharge, current should be zero when RWL gets high.
- However, due to a voltage bump (blfi gets charged up), both M7 and M8 experience a partial turn-on, represented by I\_partial\_on.





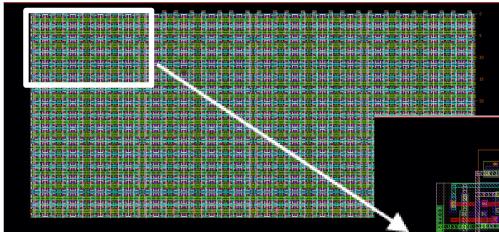


#### **Bitcell Area:**

1.28x3.23 = 4.134 μm<sup>2</sup>

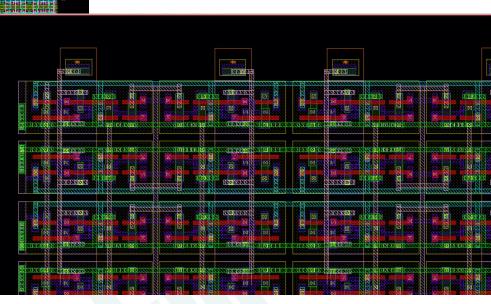
## Layout of 32X32 Array





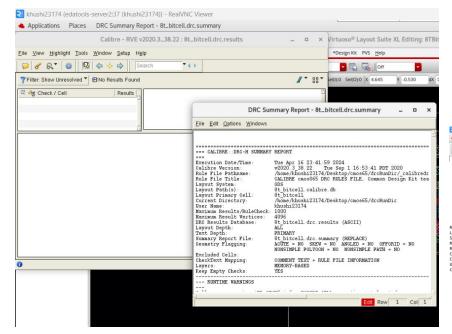
#### 32x32 Array Area:

46.735x109.175= 5102.2936 μm<sup>2</sup>



#### DRC and LVS clean Reports





khushi23174 (edal Applications Pla		i23174)) - RealVNC Viewer	
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	••••••	CELL SUMMARY	
Result	Layout 8t_sram_lvs	Source 8t_sram_lvs	
	*************	LVS PARAMETERS	

#### **Conclusions and Future Plans:**



#### Technical conclusions

- Designed and analysed 8T sram cell, design specifications were met.
- Accomplished denser **32x32** SRAM cell array using technique of flipping and sharing.
- We successfully achieved custom layout design using Virtuoso, ensuring precise control over the placement and routing to meet minimum area constraint.

#### **♦** Emphasise on learning from the project

- ❖ We were able to practically implement concepts related to SNM, statistics for VLSI and sram cell design.
- ❖ We utilize Virtuoso for schematic design and layout creation, ensuring LVS and DRC via Calibre.
- Post-layout parasitic extraction is performed using PEX.
- For evaluation FOMs and Monte Carlo simulations were done using Eldo and analyze waveforms with EZwave to validate and optimize our design for given specifications.
- Parasitic extraction degraded FOMs of cell to some extent.

#### **♦** Future plans

- FOMs can be compared with different bitcells (viz. 6T, 8T 2R/W, 10T etc) for application specific analysis.
- ♣ Impact of parasitic extraction can be lowered by having performance oriented design approach.
- ❖ Performance improved 8T sram cell can be employed for IMC applications.

#### References



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- Simulations: "Eldo." Siemens EDA. [Online]. Available: https://eda.sw.siemens.com/en-US/ic/eldo/. [Accessed: March 10, 2024].
- Waveform Viewer: "EZwave." Siemens EDA. [Online]. Available: https://www.eda-solutions.com/products/ezwave/. [Accessed: March 10, 2024].

## **Work Distribution**



Schematic Design, Layout and Array	Sizing and PVT Conditions	FOMs and Simulations
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Vansh Singhai	Khushi Kasbe	Gangaprasad Horke